TOSHIBA Field-Effect Transistor Silicon P-Channel MOS Type (U-MOSVI)

# SSM3J130TU

## Power Management Switch Applications

- 1.5 V drive
- Low ON-resistance: $R_{DS(ON)}$  = 63.2 m $\Omega$  (max) (@V<sub>GS</sub> = -1.5 V)

 $R_{DS(ON)} = 41.1 \text{ m}\Omega \text{ (max) } (@V_{GS} = -1.8 \text{ V})$ 

 $R_{DS(ON)} = 31.0 \text{ m}\Omega \text{ (max) (@V_{GS} = -2.5 V)}$ 

 $R_{DS(ON)} = 25.8 \text{ m}\Omega \text{ (max) } (@V_{GS} = -4.5 \text{ V})$ 

# Absolute Maximum Ratings (Ta = 25°C)

| Characteristic            |       | Symbol                  | Rating     | Unit |  |
|---------------------------|-------|-------------------------|------------|------|--|
| Drain-Source voltage      |       | V <sub>DSS</sub>        | -20        | V    |  |
| Gate-Source voltage       |       | V <sub>GSS</sub>        | ± 8        | V    |  |
| Drain current             | DC    | I <sub>D</sub>          | -4.4       | Α    |  |
|                           | Pulse | I <sub>DP</sub>         | -8.8       |      |  |
| Power dissipation         |       | P <sub>D</sub> (Note 1) | 800        | - mW |  |
|                           |       | P <sub>D</sub> (Note 2) | 500        |      |  |
| Channel temperature       |       | T <sub>ch</sub>         | 150        | °C   |  |
| Storage temperature range |       | T <sub>stg</sub>        | -55 to 150 | °C   |  |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Mounted on a ceramic board.

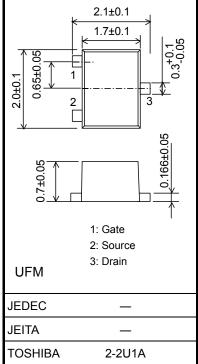
 $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 0.8 \text{ mm}, \text{ Cu Pad: } 645 \text{ mm}^2)$ 

Note 2: Mounted on an FR4 board.

 $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 1.6 \text{ mm}, \text{Cu Pad: } 645 \text{ mm}^2)$ 

# 2.1±0.1 1.7±0.1

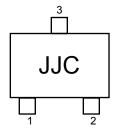
Unit: mm

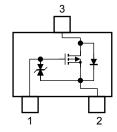


Weight: 6.6 mg (typ.)

#### Marking

## **Equivalent Circuit (top view)**





#### **Electrical Characteristics (Ta = 25°C)**

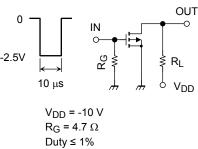
| Chara                          | cteristic            | Symbol  | Test Conditions  |          | Min  | Тур. | Max  | Unit |
|--------------------------------|----------------------|---|--|----------|------|------|------|------|
| Drain Source breakdown voltege | V (BR) DSS           | I <sub>D</sub> = -1 mA, V <sub>GS</sub> = 0 V     |  | -20      | _    | _    | V    |      |
| Drain-Source breakdown voltage |                      | V (BR) DSX  | I <sub>D</sub> = -1 mA, V <sub>GS</sub> = 5 V  | (Note 4) | -15  | _    | _    | v    |
| Drain cut-off curre            | nt                   | I <sub>DSS</sub>                                  | V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0 V                                       |          | _    | _    | -1   | μА   |
| Gate leakage curre             | ent                  | I <sub>GSS</sub>                                  | $V_{GS} = \pm 8 \text{ V}, V_{DS} = 0 \text{ V}$                                     |          | _    | _    | ±1   | μА   |
| Gate threshold vol             | tage                 | V <sub>th</sub>                                   | $V_{DS} = -3 \text{ V}, I_{D} = -1 \text{ mA}$                                       |          | -0.3 | _    | -1.0 | V    |
| Forward transfer a             | dmittance            | Y <sub>fs</sub>                                   | V <sub>DS</sub> = -3 V, I <sub>D</sub> = -2.0 A                                      | (Note 3) | 8.8  | 17.5 | _    | S    |
| Drain-source ON-resistance     | R <sub>DS</sub> (ON) | I <sub>D</sub> = -4.0 A, V <sub>GS</sub> = -4.5 V | (Note 3)   | _        | 20.9 | 25.8 | · mΩ |      |
|                                |                      | I <sub>D</sub> = -4.0 A, V <sub>GS</sub> = -2.5 V | (Note 3)   | _        | 24.2 | 31.0 |      |      |
|                                |                      | I <sub>D</sub> = -2.5 A, V <sub>GS</sub> = -1.8 V | (Note 3)   | _        | 28.8 | 41.1 |      |      |
|                                |                      | I <sub>D</sub> = -1.5 A, V <sub>GS</sub> = -1.5 V | (Note 3)   | _        | 32.4 | 63.2 |      |      |
| Input capacitance              |                      | C <sub>iss</sub>                                  | V = 40.V V = 0.V   |          | _    | 1800 | _    |      |
| Output capacitance             |                      | Coss  | $V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}$ $f = 1 \text{ MHz}$                   |          | _    | 205  | _    | pF   |
| Reverse transfer capacitance   |                      | C <sub>rss</sub>                                  | 1 - 1 1011 12  |          | _    | 190  | _    |      |
| Switching time                 | Turn-on time         | t <sub>on</sub>                                   | $V_{DD}$ = -10 V, $I_{D}$ = -1.5 A<br>$V_{GS}$ = 0 to -2.5 V, $R_{G}$ = 4.7 $\Omega$ |          | _    | 25   | _    | ns   |
|                                | Turn-off time        | t <sub>off</sub>                                  |  |          | _    | 133  | _    | 115  |
| Total Gate Charge              |                      | Qg  | V <sub>DS</sub> = -10 V, I <sub>DS</sub> = - 4.4 A,                                  |          | _    | 24.8 | _    |      |
| Gate-Source Charge             |                      | Qgs   | $V_{GS} = -10 \text{ V}, I_{DS} = -4.4 \text{ A},$<br>$V_{GS} = -4.5 \text{ V}$      |          | _    | 18.0 | _    | nC   |
| Gate-Drain Charge              |                      | Q <sub>gd</sub>                                   | V GS 4.5 V   |          | _    | 6.8  | _    | , ]  |
| Drain-Source forward voltage   |                      | V <sub>DSF</sub>                                  | I <sub>D</sub> = 4.4 A, V <sub>GS</sub> = 0 V  | (Note 3) | _    | 0.83 | 1.2  | V    |

Note3: Pulse test

Note4: If a forward bias is applied between gate and source, this device enters V(BR)DSX mode. Note that the drain-source breakdown voltage is lowered in this mode.

## **Switching Time Test Circuit**



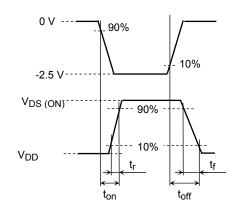


 $V_{IN}$ :  $t_r$ ,  $t_f < 5$  ns Common Source

Ta = 25°C

#### (b) V<sub>IN</sub>

(c) Vout



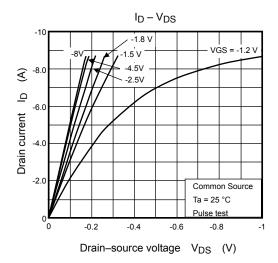
#### **Usage Considerations**

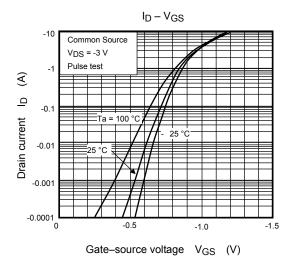
Let V<sub>th</sub> be the voltage applied between gate and source that causes the drain current (I<sub>D</sub>) to below -1 mA for the SSM3J130TU. Then, for normal switching operation,  $V_{GS(on)}$  must be higher than  $V_{th}$ , and  $V_{GS(off)}$  must be lower than  $V_{th}$ . This relationship can be expressed as:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ .

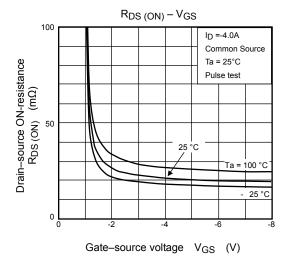
Take this into consideration when using the device.

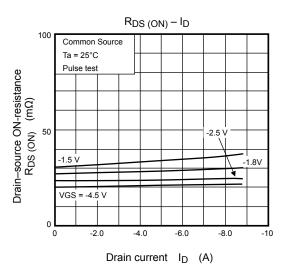
#### **Handling Precaution**

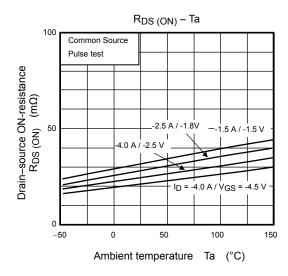
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

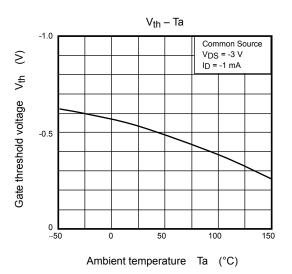


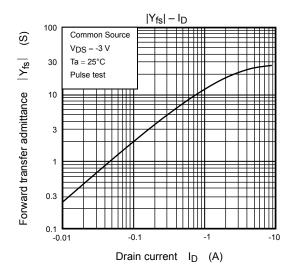


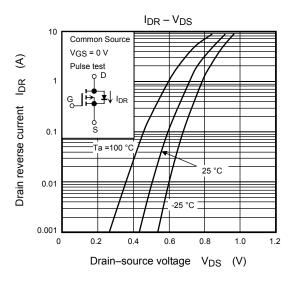


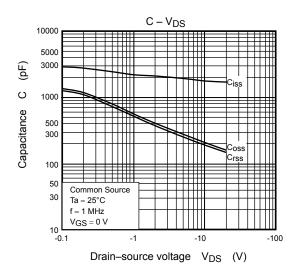


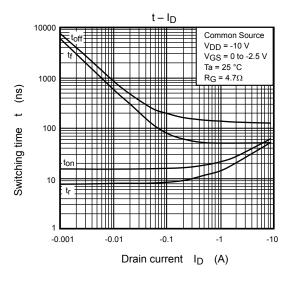


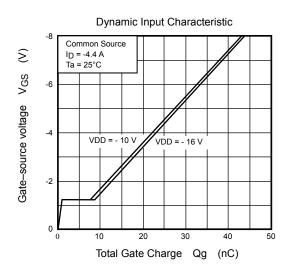




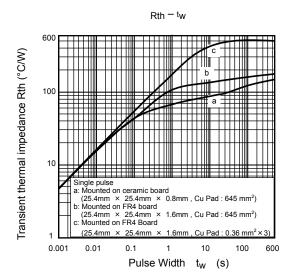


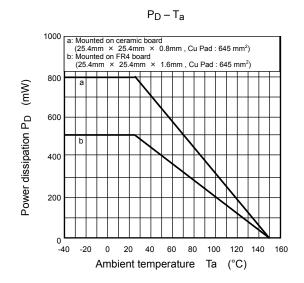






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